

	Hits	Search Text	DBs
3	1	((substrate or wafer or workpiece) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5)) and ((photoresist or resist or polyimide) near26 (pattern or lithograph\$4 or photolithograph\$4)) and ((exposed or unmasked or stripped or aperture or via or hole or trench) near26 (region or area or portion) near33 (adsorb\$4 or plat\$4 or nucleat\$4) near26 (ionic or electroless or electrolytic) near24 (solution or colloid\$4 or suspension) near32 (metal\$4 or chromium or Cr or Mo or Ta or nickel or Ni or alloy))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
4	1	((substrate or wafer or workpiece) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5)) and ((photoresist or resist or polyimide) near12 (pattern or lithograph\$4 or photolithograph\$4)) and ((exposed or unmasked or stripped or aperture or via or hole or trench) near26 (region or area or portion) near33 (adsorb\$4 or plat\$4 or nucleat\$4) near26 (ionic or electroless or electrolytic) near24 (solution or colloid\$4 or suspension) near32 (metal\$4 or chromium or Cr or Mo or Ta or nickel or Ni or alloy))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	1	((substrate or wafer or workpiece) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5 or mask\$4)) and ((photoresist or resist or polyimide) near12 (pattern\$4 or lithograph\$4 or photolithograph\$4)) and ((exposed or unmasked or stripped or aperture or via or hole or trench or selective\$4) near26 (region or area or portion) near33 (adsorb\$4 or plat\$4 or nucleat\$4) near26 (ionic or electroless or electrolytic) near24 (solution or colloid\$4 or suspension) near32 (metal\$4 or chromium or Cr or Mo or Ta or nickel or Ni or alloy))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
6	1	((substrate or wafer or workpiece) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5 or mask\$4)) and ((photoresist or resist or polyimide) near12 (pattern\$4 or lithograph\$4 or photolithograph\$4)) and ((exposed or unmasked or stripped or aperture or via or hole or trench or selective\$4) near26 (region or area or portion) near33 (adsorb\$4 or plat\$4 or nucleat\$4 or coat\$4 or adher\$4) near26 (ionic or electroless or electrolytic) near24 (solution or colloid\$4 or suspension) near32 (metal\$4 or chromium or Cr or Mo or Ta or nickel or Ni or alloy))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
7	0	((substrate or wafer or workpiece or surface) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5 or (radiation near4 sensitive near4 layer) near16 (pattern or mask))) and ((photoresist or resist or polyimide) near12 (pattern\$4 or lithograph\$4 or photolithograph\$4 or mask)) and (selective\$4 near26 (region or area or portion) near33 (adsorb\$4 or plat\$4 or nucleat\$4 or coat\$4 or adher\$4 or metal\$5) near26 (ionic or electroless or electrolytic or plat\$4) near24 (solution or colloid\$4 or suspension) near32 (metal\$4 or chromium or Cr or Mo or Ta or nickel or Ni or alloy) near16 (ITO or (indium near3 tin near3 oxide)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
8	4	((substrate or wafer or workpiece or surface) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5 or (radiation near4 sensitive near4 layer) near16 (pattern or mask))) and ((photoresist or resist or polyimide) near12 (pattern\$4 or lithograph\$4 or photolithograph\$4 or mask)) and (selective\$4 near26 (region or area or portion) near33 (adsorb\$4 or plat\$4 or nucleat\$4 or coat\$4 or adher\$4 or metal\$5) near26 (ionic or electroless or electrolytic or plat\$4) near24 (solution or colloid\$4 or suspension) near16 (ITO or (indium near3 tin near3 oxide)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
9	4	((substrate or wafer or workpiece or surface) near34 (ITO or (indium near2 tin near3 oxide)) near35 (resist or photoresist or polyimide or photocur\$5 or (radiation near4 sensitive near4 layer) near16 (pattern or mask))) and ((photoresist or resist or polyimide) near12 (pattern\$4 or lithograph\$4 or photolithograph\$4 or mask)) and (selective\$4 near26 (region or area or portion or site or exposed) near33 (adsorb\$4 or plat\$4 or nucleat\$4 or coat\$4 or adher\$4 or metal\$5) near26 (ionic or electroless or electrolytic or plat\$4) near24 (solution or colloid\$4 or suspension) near16 (ITO or (indium near3 tin near3 oxide)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
10	32	(substrate or wafer or device or platen or surface) near16 (ITO or (indium near4 tin near4 oxide) same (mask or pattern) same (resist or photoresist)) and ((metal\$4 or plat\$4) same (selective near28 (region or site or area or portion or exposed or portion)) same (ITO or (indium near9 tin near9 oxide))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
11	7	((substrate or wafer or device or platen or surface) near16 (ITO or (indium near4 tin near4 oxide))) same (mask or pattern) same (resist or photoresist or photolithograph\$4 or lithograph\$5)) and ((metal\$4 or plat\$4 or (cataly\$4 near12 metal\$4)) same (selective near28 (region or site or area or portion or exposed or portion)) same (ITO or (indium near9 tin near9 oxide))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
12	0	((ITO or (indium near4 tin near4 oxide)) same (electroless near4 plating) same (solution or suspension) same (stabiliz\$5 same (tin or Sn))) and ((electroless near4 plat\$4) same (ITO or (indium near4 tin near4 oxide)) same (((dry\$4 or dried) near22 oven) or heat\$4 or bak\$4 or anneal) same ((blow\$4 near6 gas\$3) or (gas near4 inject\$4))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
13	0	((ITO or (indium near4 tin near4 oxide)) same (electroless near4 plating) same (solution or suspension) same (stabiliz\$5 same (tin or Sn))) and ((electroless near4 plat\$4) same (ITO or (indium near4 tin near4 oxide)) same (((dry\$4 or dried) near22 oven) or heat\$4 or bak\$4 or anneal) same ((blow\$4 near6 (air or gas\$3)) or ((gas or air or pressur\$4) near4 inject\$4))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
14	2	((ITO or (indium near4 tin near4 oxide)) same (electroless near4 plating) same (solution or suspension) same (stabiliz\$5 same (tin or Sn)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
15	0	((electroless near4 plat\$4) same (ITO or (indium near4 tin near4 oxide)) same (((dry\$4 or dried) near22 oven) or heat\$4 or bak\$4 or anneal) same ((blow\$4 near6 (air or gas\$3)) or ((gas or air or pressur\$4) near4 inject\$4))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
16	14	((plat\$4) same (ITO or (indium near4 tin near4 oxide)) same (((dry\$4 or dried) near22 oven) or heat\$4 or bak\$4 or anneal) same ((blow\$4 near6 (air or gas\$3)) or ((gas or air or pressur\$4) near4 inject\$4))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB